



Dual, 12-Bit, Parallel Input, Multiplying Digital-to-Analog Converter

FEATURES

- $\pm 1\text{LSB INL}$
- 2.5V to 5.5V Supply Operation
- Fast Parallel Interface:
17ns Write Cycle
- Update Rate of 20.4MSPS
- 10MHz Multiplying Bandwidth
- $\pm 15\text{V}$ Reference Input
- Extended Temperature Range:
 -40°C to $+125^{\circ}\text{C}$
- 40-Lead QFN
- 12-Bit Monotonic
- 4-Quadrant Multiplication
- Power-On Reset with Brownout Detection
- Readback Function
- Industry-Standard Pin Configuration
- Pin-Compatible with the AD5405

APPLICATIONS

- Portable Battery-Powered Instruments
- Waveform Generators
- Analog Processing
- Programmable Amplifiers and Attenuators
- Digitally-Controlled Calibration
- Programmable Filters and Oscillators
- Ultrasound

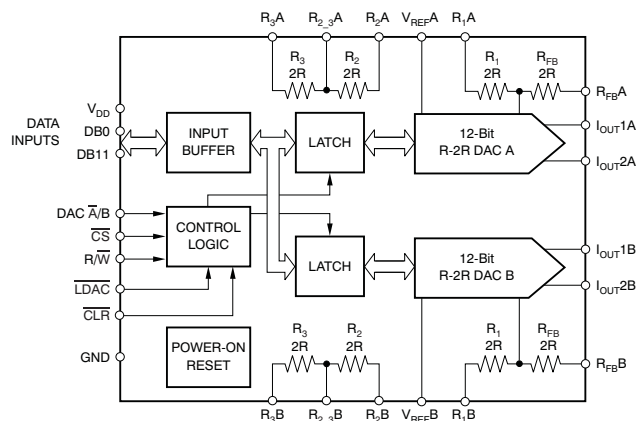
DESCRIPTION

The DAC7822 is a dual, CMOS, 12-bit, current output digital-to-analog converter (DAC). This device operates from a 2.5V to 5.5V power supply, making it suitable for battery-powered and many other applications.

The DAC7822 operates with a fast parallel interface. Data readback allows the user to read the contents of the DAC register via the DB pins. On power-up, the internal register and latches are filled with zeroes and the DAC outputs are at zero scale.

The DAC7822 offers excellent 4-quadrant multiplication characteristics, with large signal multiplying bandwidth of 10MHz. The applied external reference input voltage (V_{REF}) determines the full-scale output current. An integrated feedback resistor (R_{FB}) provides temperature tracking and full-scale voltage output when combined with an external current-to-voltage precision amplifier. The DAC7822 also includes the resistors necessary for 4-quadrant multiplication and other configuration modes.

The DAC7822 is available in a 40-lead QFN package.



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION⁽¹⁾

PRODUCT	PACKAGE	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
DAC7822	40-QFN	RTA	–40°C to +125°C	DAC7822	DAC7822IRTAT	250, Tape and Reel
					DAC7822IRTAR	2000, Tape and Reel

(1) For the most current specifications and package information, see the Package Option Addendum at the end of this data sheet, or refer to our web site at www.ti.com.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

	DAC7822	UNIT
V_{DD} to GND	–0.3 to +7.0	V
Digital input voltage to GND	–0.3 to $V_{DD} + 0.3$	V
V_{OUT} to GND	–0.3 to $V_{DD} + 0.3$	V
Operating temperature range	–40 to +125	°C
Storage temperature range	–65 to +150	°C
Junction temperature (T_J max)	+150	°C
ESD Rating, HBM	2000	V
ESD Rating, CDM	1000	V

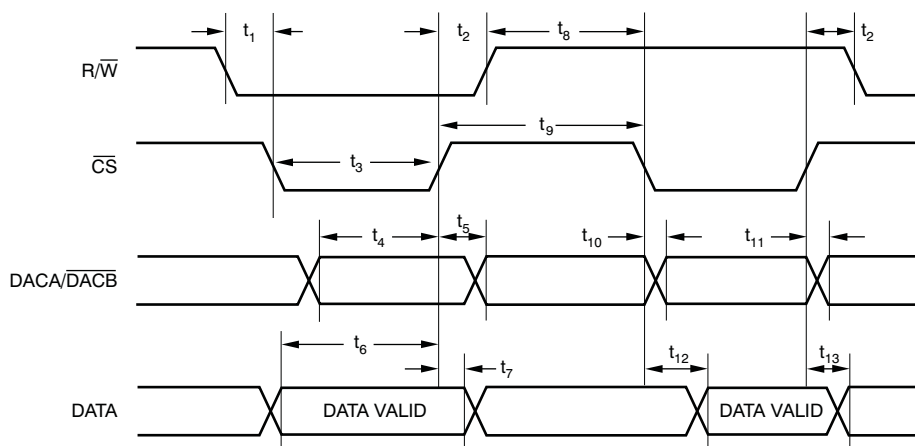
(1) Stresses above those listed under absolute maximum ratings may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

$V_{DD} = +2.5V$ to $+5.5V$; $I_{OUT1} = \text{Virtual GND}$; $I_{OUT2} = 0V$; $V_{REF} = 10V$; $T_A = \text{full operating temperature}$. All specifications $-40^{\circ}C$ to $+125^{\circ}C$, unless otherwise noted.

PARAMETER	CONDITIONS	DAC7822			UNITS
		MIN	TYP	MAX	
STATIC PERFORMANCE					
Resolution		12			Bits
Relative accuracy				±1	LSB
Differential nonlinearity				±1	LSB
Output leakage current	Data = 000h, T _A = +25°C			±1	nA
Output leakage current	Data = 000h, T _A = T _{MAX}			±15	nA
Full-scale gain error	All ones loaded to DAC register		±10	±25	mV
Full-scale tempco ⁽¹⁾			±5		ppm/°C
Bipolar zero-code error	Circuit configuration as shown in Figure 41			±25	mV
Output capacitance	DAC latches leaded with all 1s		25	30	pF
REFERENCE INPUT					
V _{REF} range		−15		15	V
V _{REF} A, V _{REF} B, Input resistance		8	10	12	kΩ
R ₁ , R _{FB} resistance		17	20	25	kΩ
R ₂ , R ₃ resistance		17	20	25	kΩ
V _{REF} A to V _{REF} B Input Mismatch			1.6	2.5	%
R ₂ to R ₃ Mismatch			0.06	0.18	%
LOGIC INPUTS AND OUTPUT ⁽¹⁾					
Input low voltage	V _{IL}	V _{DD} = +2.5V		0.6	V
		V _{DD} = +5V		0.8	V
Input high voltage	V _{IH}	V _{DD} = +2.5V	2.1		V
		V _{DD} = +5V	2.4		V
Input leakage current	I _{IL}			1	μA
Input capacitance	C _{IL}			10	pF
POWER REQUIREMENTS					
V _{DD}		2.5		5.5	V
I _{DD} (normal operation)	Logic inputs = 0V			5	μA
V _{DD} = +4.5V to +5.5V	V _{IH} = V _{DD} and V _{IL} = GND		0.8	5	μA
V _{DD} = +2.5V to +3.6V	V _{IH} = V _{DD} and V _{IL} = GND		0.4	2.5	μA
AC CHARACTERISTICS ⁽¹⁾					
Output voltage settling time				0.2	μs
Reference multiplying BW	V _{REF} = 7V _{PP} , Data = FFFh		10		MHz
DAC glitch impulse	V _{REF} = 0V to 10V, Data = 7FFh to 800h to 7FFh		10		nV-s
Feedthrough error V _{OUT} /V _{REF}	Data = 000h, V _{REF} = 100kHz		−70		dB
Digital feedthrough			2		nV-s
Total harmonic distortion			−105		dB
Output spot noise voltage			25		nV/√Hz

(1) Specified by design and characterization; not production tested.

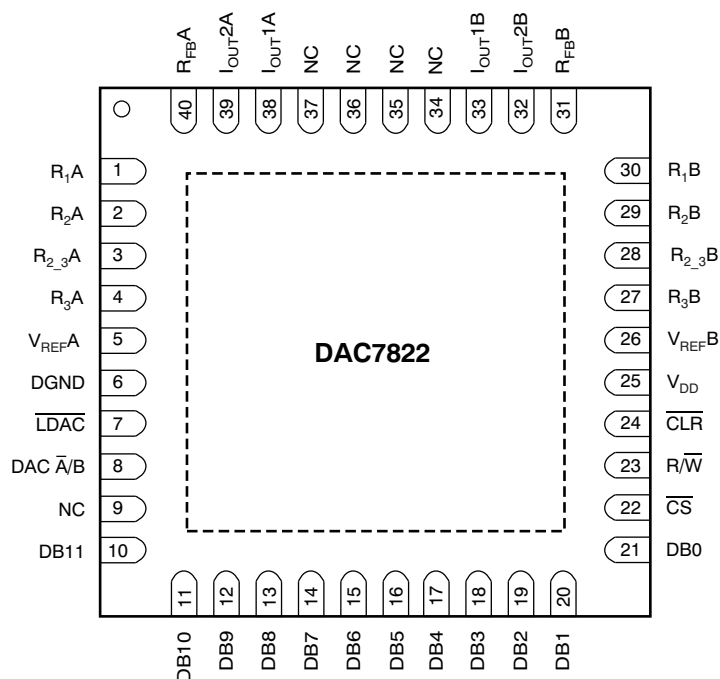
TIMING INFORMATION**TIMING REQUIREMENTS: 2.5 V to 5.5 V**

At $t_r = t_f = 1\text{ ns}$ (10% to 90% of V_{DD}) and timed from a voltage level of $(V_{IL} + V_{IH})/2$; $V_{DD} = 2.5\text{ V to } 5.5\text{ V}$, $V_{REF} = 10\text{ V}$, $I_{OUT2} = 0\text{ V}$. All specifications -40°C to $+125^\circ\text{C}$, unless otherwise noted.

PARAMETER ⁽¹⁾	TEST CONDITIONS	DAC7822			UNIT
		MIN	TYP	MAX	
t_1	R/\overline{W} to \overline{CS} setup time	0			ns
t_2	R/\overline{W} to \overline{CS} hold time	0			ns
t_3	\overline{CS} low time (write cycle)	10			ns
t_4	Address setup time	10			ns
t_5	Address hold time	0			ns
t_6	Data setup time	6			ns
t_7	Data hold time	0			ns
t_8	R/\overline{W} high to \overline{CS} low	5			ns
t_9	\overline{CS} minimum high time	7			ns
t_{10}	Address setup time (Read Cycle)	0			ns
t_{11}	Address hold time (Read Cycle)	0			ns
t_{12}	Data access time		5	35	ns
t_{13}	Bus relinquish time		5	10	ns

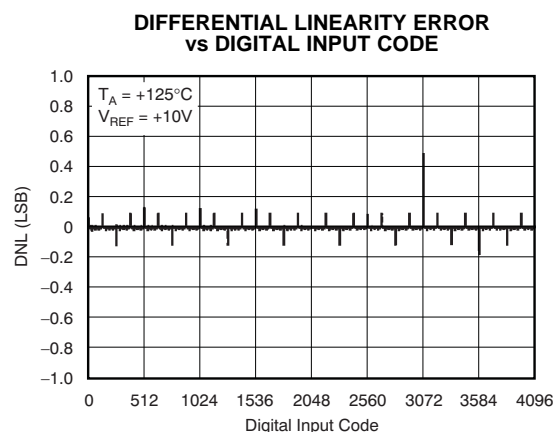
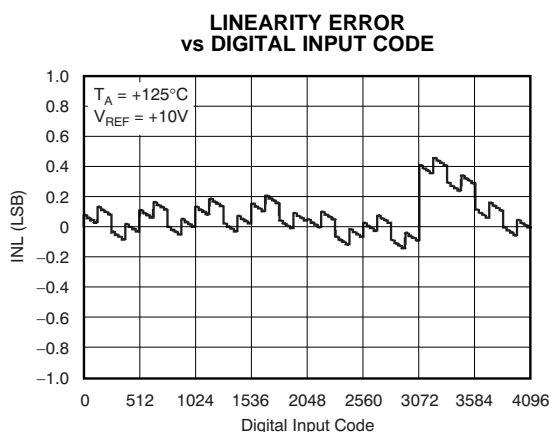
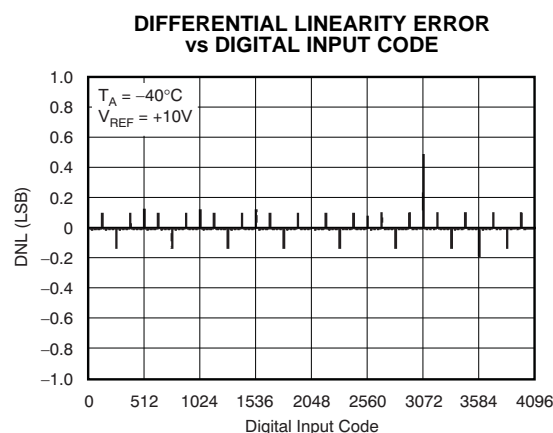
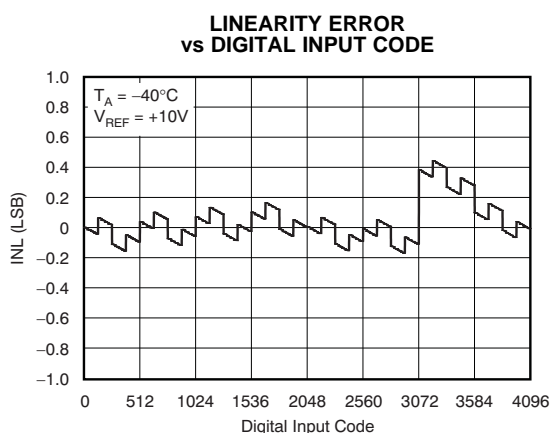
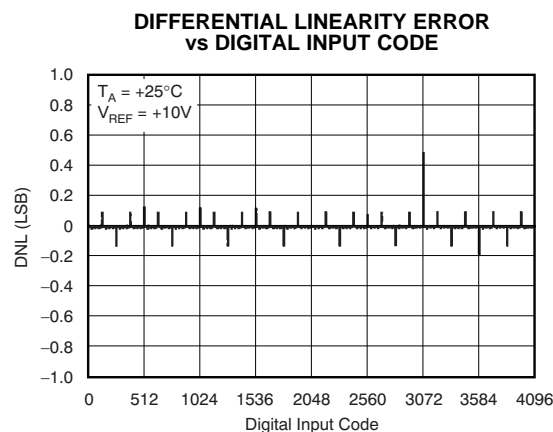
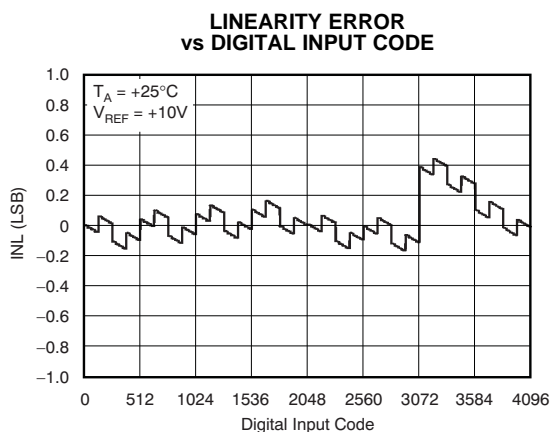
(1) Ensured by design; not production tested.

DEVICE INFORMATION



TERMINAL FUNCTIONS

PIN NO.	PIN NAME	DESCRIPTION
1-4	R ₁ A, R ₂ A, R _{2_3} A, R ₃ A	DAC A 4-Quadrant Resistors. Allows a number of configuration modes, including bipolar operation with minimum of external components.
5, 26	V _{REF} A, V _{REF} B	DAC Reference Voltage Input Terminals.
6	DGND	Digital Ground Pin.
7	LDAC	Load DAC Input. Allows asynchronous or synchronous updates to the DAC output. The DAC is asynchronously updated when this signal goes low. Alternatively, if this line is held permanently low, an automatic or synchronous update mode is selected whereby the DAC is updated on the rising edge of CS.
8	DAC A/B	Selects DAC A or B. Low selects DAC A, and high selects DAC B.
9, 34-37	NC	Not internally connected.
10-21	DB11 to DB0	Parallel Data Bits 11 through 0.
22	CS	Chip Select Input; active low. Used in conjunction with R/W to load parallel data to the input latch or to read data from the DAC register. Edge sensitive; when pulled high, the DAC data is latched.
23	R/W	Read/Write. When low, used in conjunction with CS to load parallel data. When high, used in conjunction with CS to read back contents of DAC register.
24	CLR	Active Low Control Input. Clears DAC output and input and DAC registers.
25	V _{DD}	Positive Power Supply Input. These parts can be operated from a supply of 2.5V to 5.5V.
27-30	R ₃ B, R _{2_3} B, R ₂ B, R ₁ B	DAC B 4-Quadrant Resistors. Allow a number of configuration modes, including bipolar operation with a minimum of external components.
31, 40	R _{FB} B, R _{FB} A	External Amplifier Output.
32	I _{OUT} 2B	DAC A Analog Ground. This pin typically should be tied to the analog ground of the system, but can be biased to achieve single-supply operation.
33	I _{OUT} 1B	DAC B Current Output.
38	I _{OUT} 1A	DAC A Current Output.
39	I _{OUT} 2A	DAC A Analog Ground. This pin typically should be tied to the analog ground of the system, but can be biased to achieve single-supply operation.

TYPICAL CHARACTERISTICS: $V_{DD} = +5V$ At $T_A = +25^\circ\text{C}$, $+V_{DD} = +5V$, unless otherwise noted.**Channel A**

TYPICAL CHARACTERISTICS: $V_{DD} = +5V$ (continued)

At $T_A = +25^\circ C$, $+V_{DD} = +5V$, unless otherwise noted.

Channel B

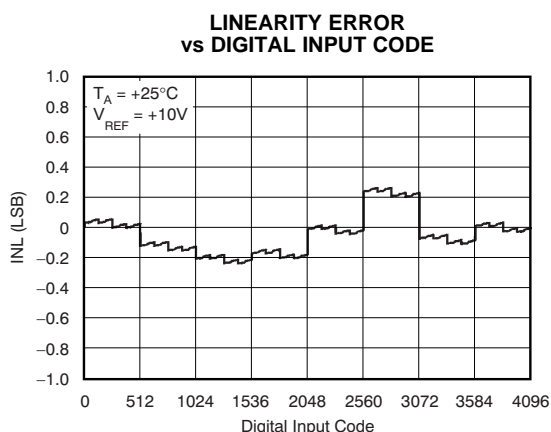


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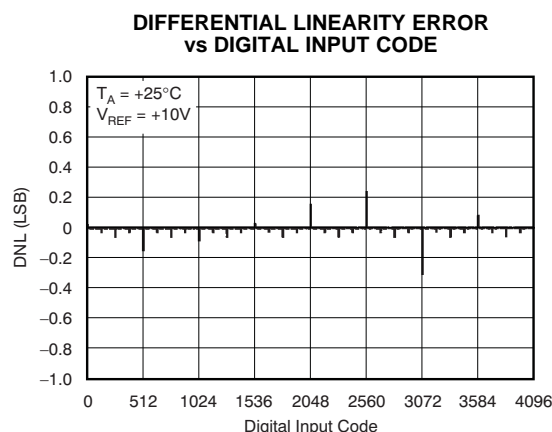


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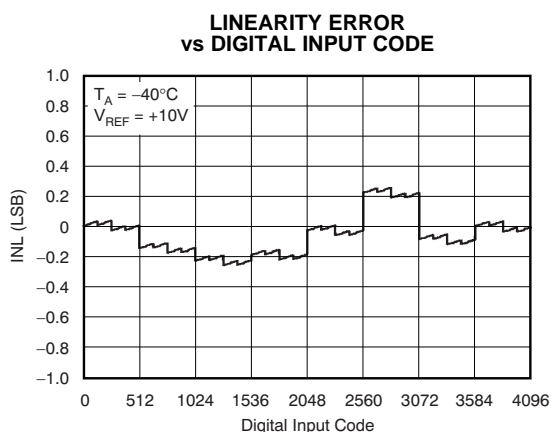


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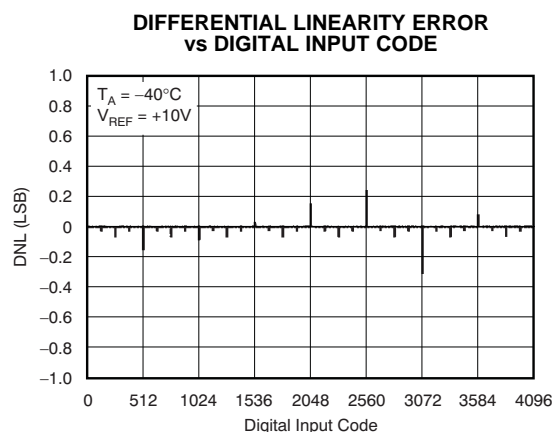


Figure 10.

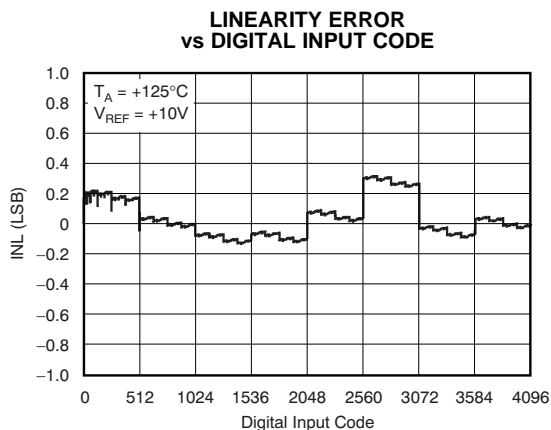


Figure 11.

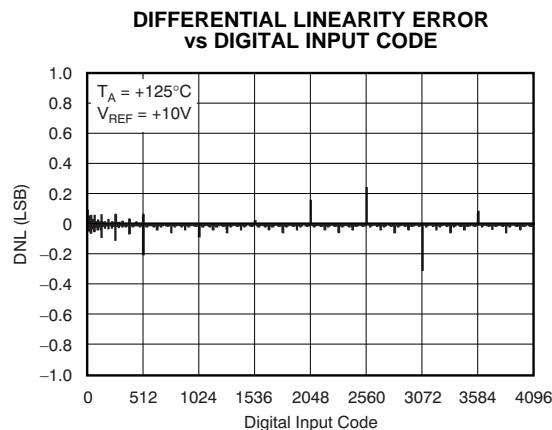


Figure 12.

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At $T_A = +25^\circ C$, $+V_{DD} = +5V$, unless otherwise noted.

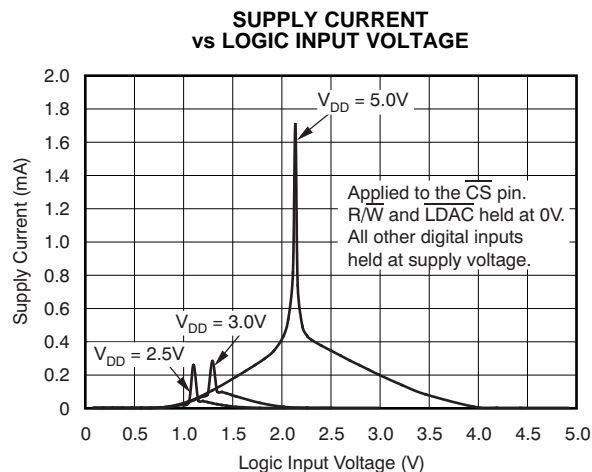


Figure 13.

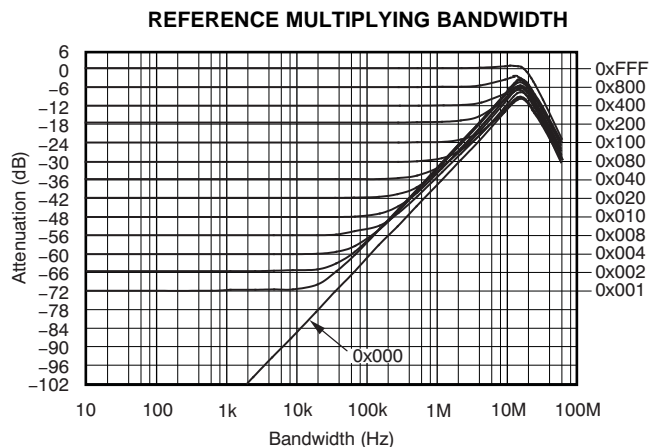


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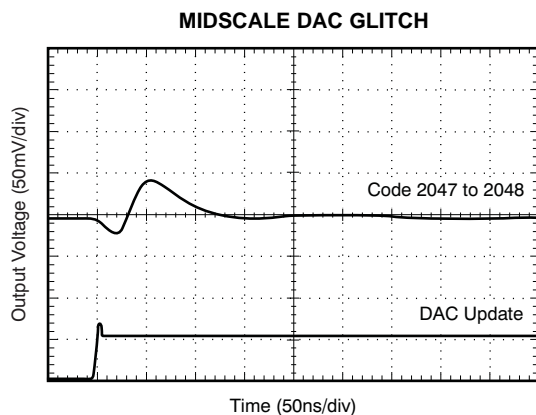


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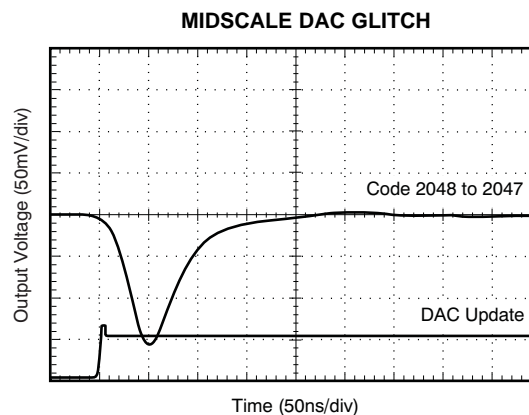


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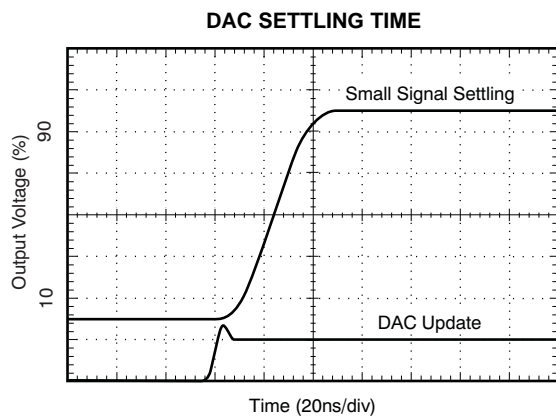


Figure 17.

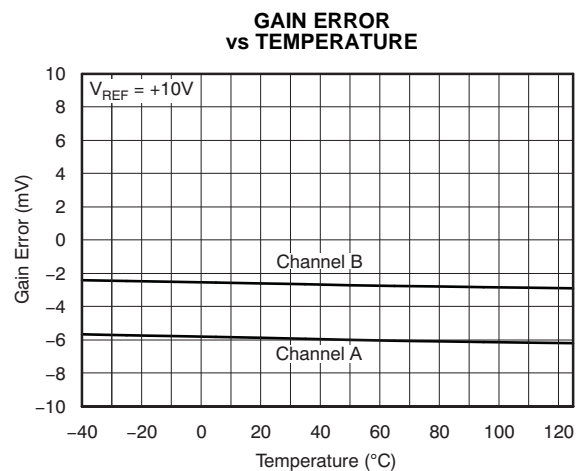


Figure 18.

TYPICAL CHARACTERISTICS: $V_{DD} = +5V$ (continued)

At $T_A = +25^\circ C$, $+V_{DD} = +5V$, unless otherwise noted.

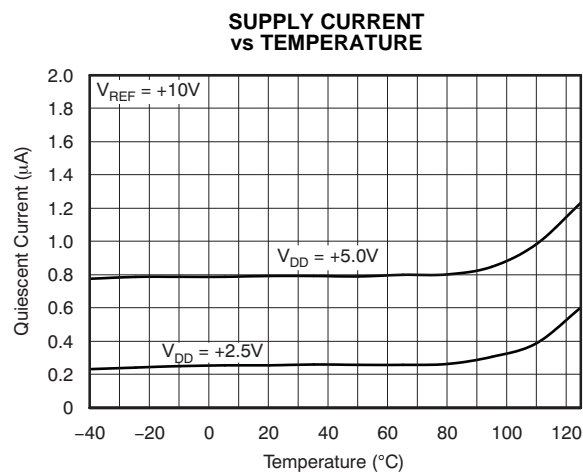


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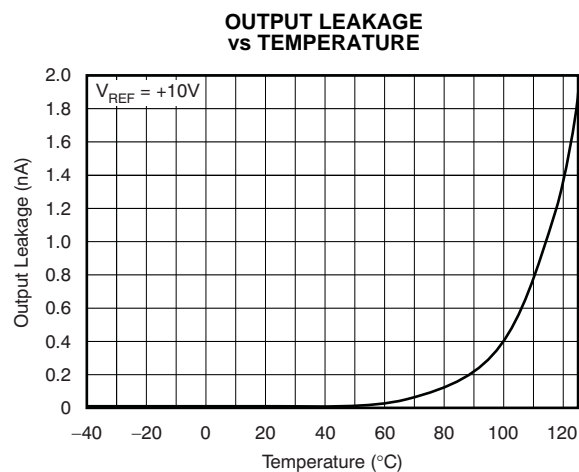
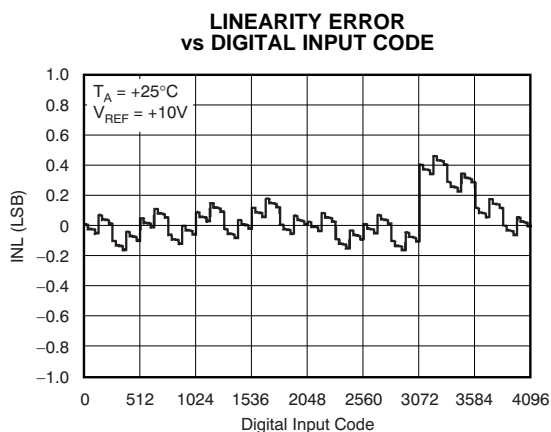
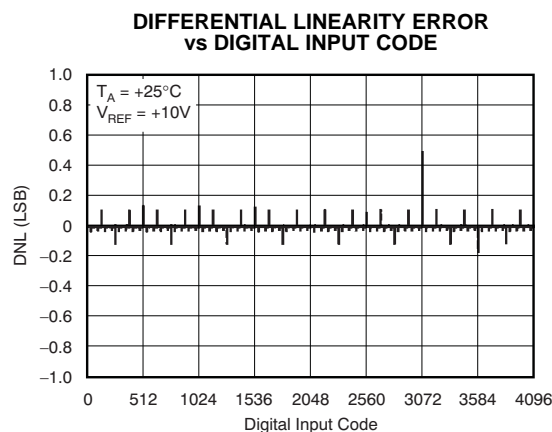
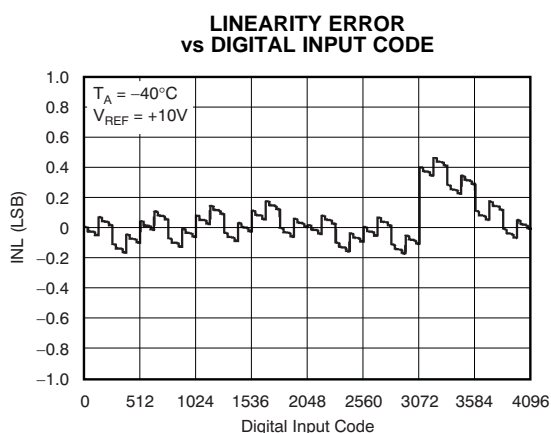
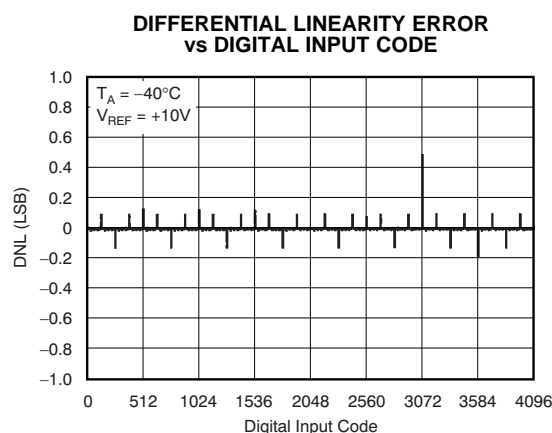
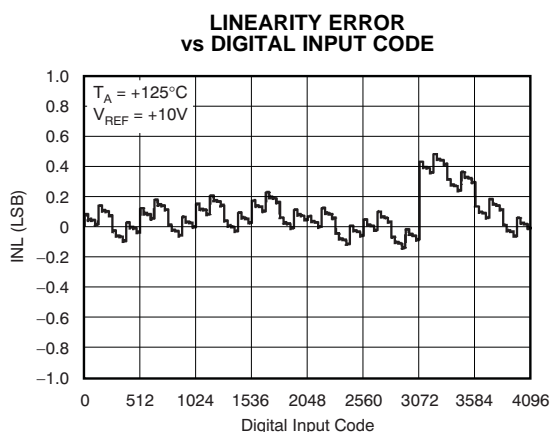
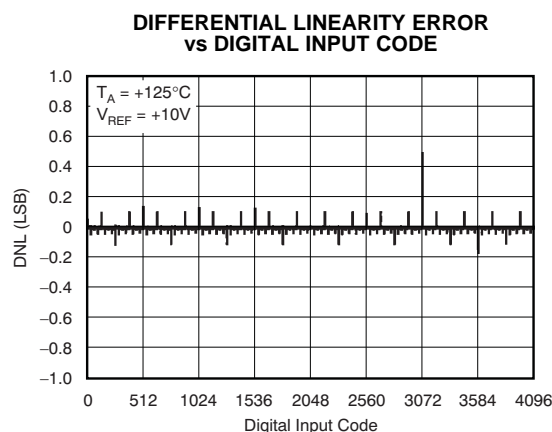


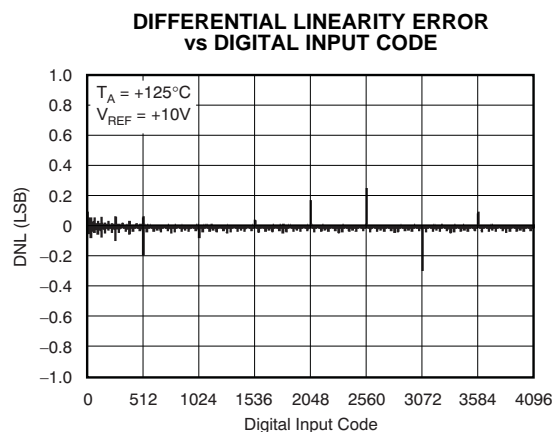
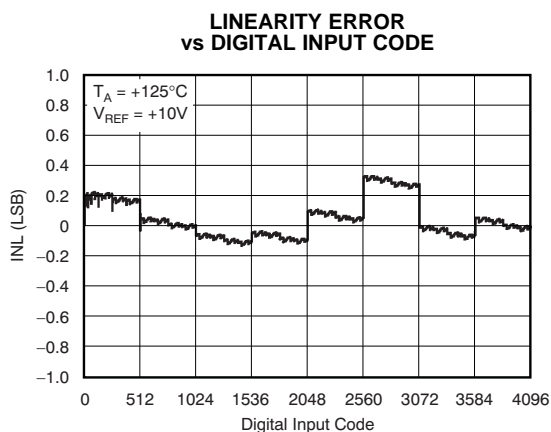
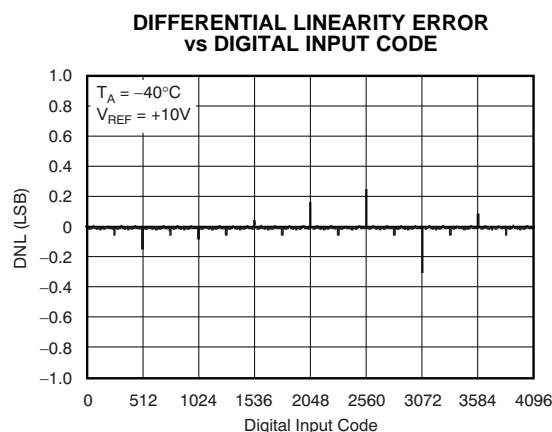
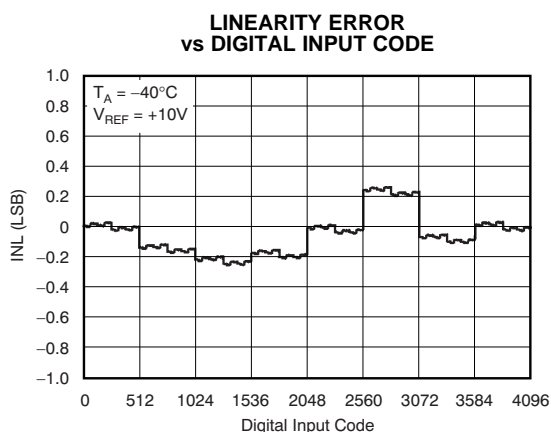
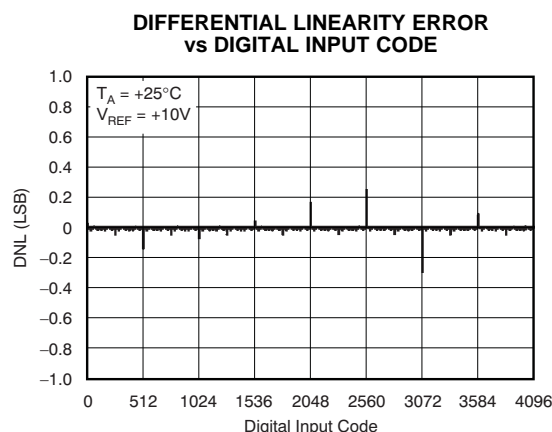
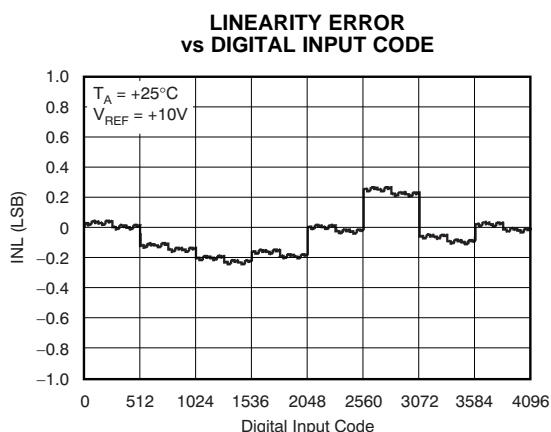
Figure 20.

TYPICAL CHARACTERISTICS: $V_{DD} = +2.5V$ At $T_A = +25^\circ\text{C}$, $+V_{DD} = +2.5V$, unless otherwise noted.**Channel A****Figure 21.****Figure 22.****Figure 23.****Figure 24.****Figure 25.****Figure 26.**

TYPICAL CHARACTERISTICS: $V_{DD} = +2.5V$ (continued)

At $T_A = +25^\circ C$, $+V_{DD} = +2.5V$, unless otherwise noted.

Channel B



TYPICAL CHARACTERISTICS: $V_{DD} = +2.5V$ (continued)

At $T_A = +25^{\circ}C$, $+V_{DD} = +2.5V$, unless otherwise noted.

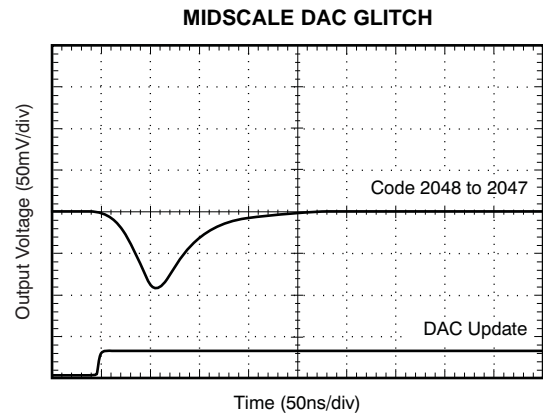


Figure 33.

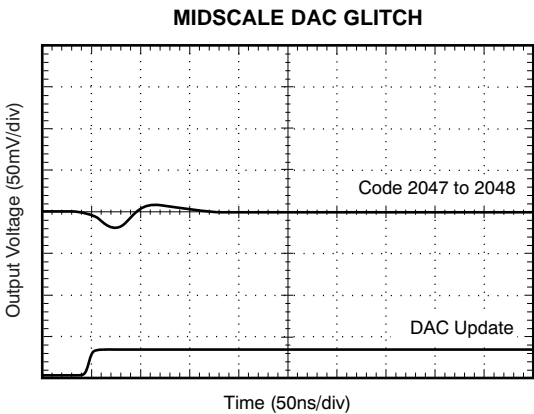


Figure 34.

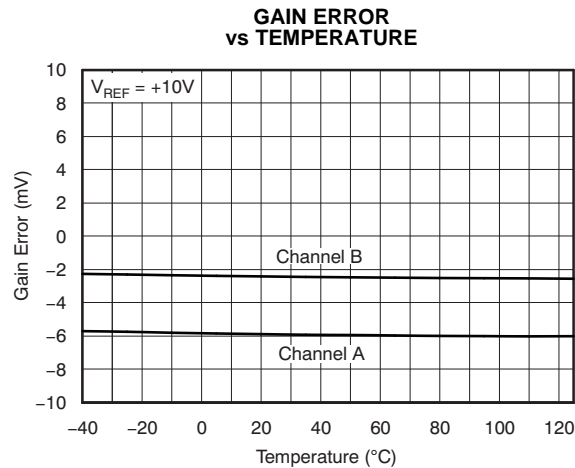


Figure 35.

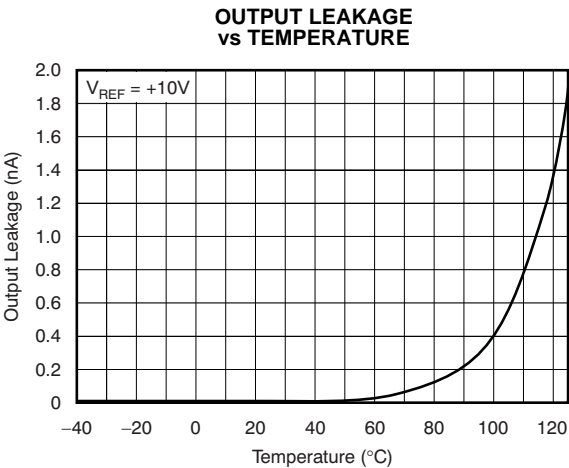


Figure 36.

THEORY OF OPERATION

The DAC7822 is a dual channel, current output, 12-bit, digital-to-analog converter (DAC). The architecture, illustrated in Figure 37, is an R-2R ladder configuration with the three MSBs segmented. Each 2R leg of the ladder is either switched to I_{OUT1} or the I_{OUT2} terminal. The I_{OUT1} terminal of the DAC is held at a virtual GND potential by the use of an external I/V converter op amp. The R-2R ladder is connected to an external reference input V_{REF} that determines the DAC full-scale current. The R-2R ladder presents a code-independent load impedance to the external reference of $10k\Omega \pm 20\%$. The external reference voltage can vary over a range of $-15V$ to $+15V$, thus providing bipolar I_{OUT} current operation. By using an external I/V converter and the DAC7822 R_{FB} resistor, output voltage ranges of $-V_{REF}$ to V_{REF} can be generated.

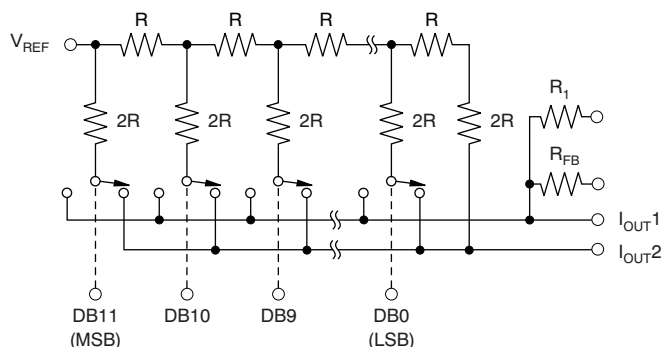


Figure 37. Equivalent R-2R DAC Circuit

When using an external I/V converter and the DAC7822 R_{FB} and R_1 resistors, the DAC output voltage is given by Equation 1:

$$V_{OUT} = -V_{REF} \times \frac{CODE}{4096} \quad (1)$$

Each DAC code determines the 2R leg switch position to either GND or I_{OUT} . Because the DAC output impedance as seen looking into the I_{OUT1} terminal changes versus code, the external I/V converter noise gain also changes. Because of this, the external I/V converter op amp must have a sufficiently low offset voltage such that the amplifier offset is not modulated by the DAC I_{OUT1} terminal impedance change. External op amps with large offset voltages can produce INL errors in the transfer function of the DAC7822 as a result of offset modulation versus DAC code.

For best linearity performance of the DAC7822, a low input offset voltage op amp (such as the OPA277) is recommended (see Figure 38). This circuit allows V_{REF} swinging from $-10V$ to $+10V$.

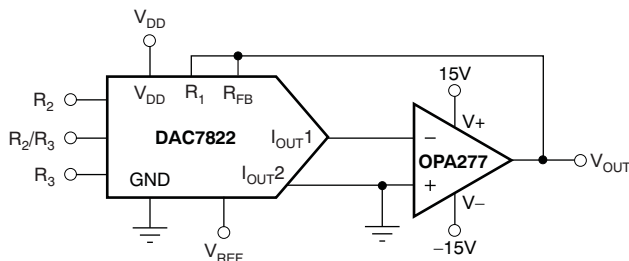


Figure 38. Voltage Output Configuration

APPLICATION INFORMATION

Stability Circuit

For a current-to-voltage design (see [Figure 39](#)), the DAC7822 current output (I_{OUT}) and the connection with the inverting node of the op amp should be as short as possible and according to correct printed circuit board (PCB) layout design. For each code change, there is a step function. If the gain bandwidth product (GBP) of the op amp is limited and parasitic capacitance is excessive at the inverting node, then gain peaking is possible. Therefore, for circuit stability, a compensation capacitor C_1 (1pF to 5pF typ) can be added to the design, as shown in [Figure 39](#).

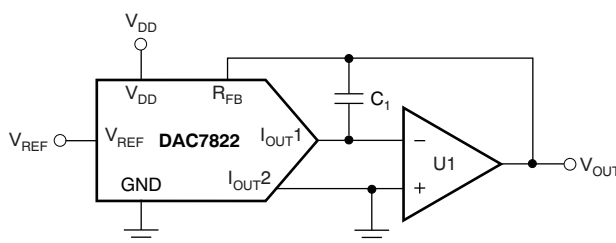


Figure 39. Gain Peaking Prevention Circuit with Compensation Capacitor

Positive Voltage Output Circuit

As [Figure 40](#) illustrates, in order to generate a positive voltage output, a negative reference is input to the DAC7822. This design is suggested instead of using an inverting amp to invert the output as a result of resistor tolerance errors. For a negative reference, V_{OUT} and GND of the reference are level-shifted to a virtual ground and a $-2.5V$ input to the DAC7822 with an op amp.

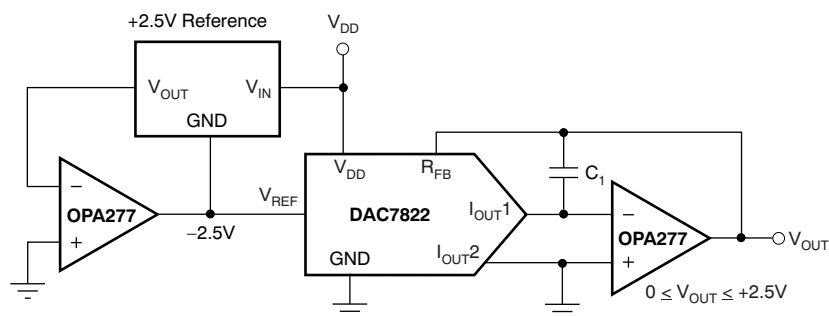


Figure 40. Positive Voltage Output Circuit

Bipolar Output Section

The DAC7822, as a 2-quadrant multiplying DAC, can be used to generate a unipolar output. The polarity of the full-scale output I_{OUT} is the inverse of the input reference voltage at V_{REF} .

Some applications require full 4-quadrant multiplying capabilities or bipolar output swing. As shown in [Figure 41](#), external op amp U2 is added as a summing amp and has a gain of 2X that widens the output span to 5V. A 4-quadrant multiplying circuit is implemented by using a 2.5V offset of the reference voltage to bias U2. According to the circuit transfer equation given in [Equation 2](#), input data (D) from code 0 to full-scale produces output voltages of $V_{OUT} = -2.5V$ to $V_{OUT} = +2.5V$.

$$V_{\text{OUT}} = \left(\frac{D}{0.5 \times 2^N} - 1 \right) \times V_{\text{REF}} \quad (2)$$

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
DAC7822IRTAR	ACTIVE	QFN	RTA	40	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
DAC7822IRTARG4	ACTIVE	QFN	RTA	40	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
DAC7822IRTAT	ACTIVE	QFN	RTA	40	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
DAC7822IRTATG4	ACTIVE	QFN	RTA	40	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

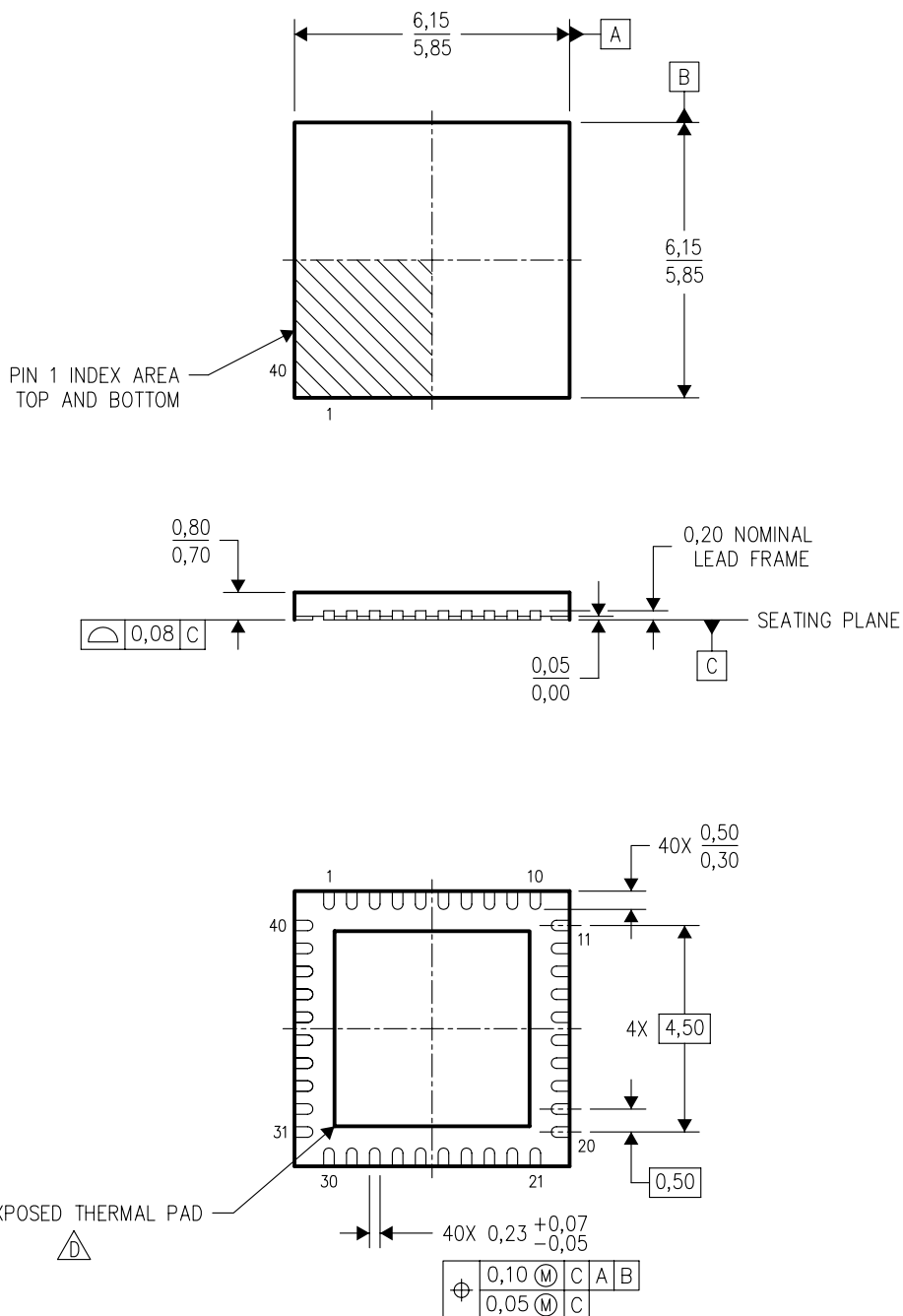
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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RTA (S-PQFP-N40)

PLASTIC QUAD FLATPACK



4204422/B 11/04

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) Package configuration.
 -  D. The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.

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